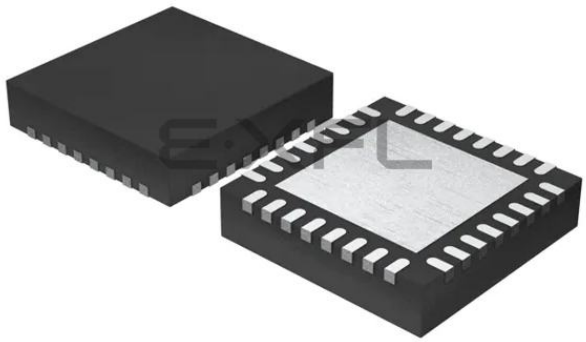

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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Discontinued at Digi-Key
Core Processor	CIP-51 8051
Core Size	8-Bit
Speed	48MHz
Connectivity	I²C, SMBus, SPI, UART/USART, USB
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	25
Program Memory Size	32KB (32K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	2.25K x 8
Voltage - Supply (Vcc/Vdd)	2.65V ~ 3.6V
Data Converters	A/D 20x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	32-VFQFN Exposed Pad
Supplier Device Package	32-QFN (5x5)
Purchase URL	https://www.e-xfl.com/product-detail/silicon-labs/efm8ub20f32g-a-qfn32

2. Ordering Information

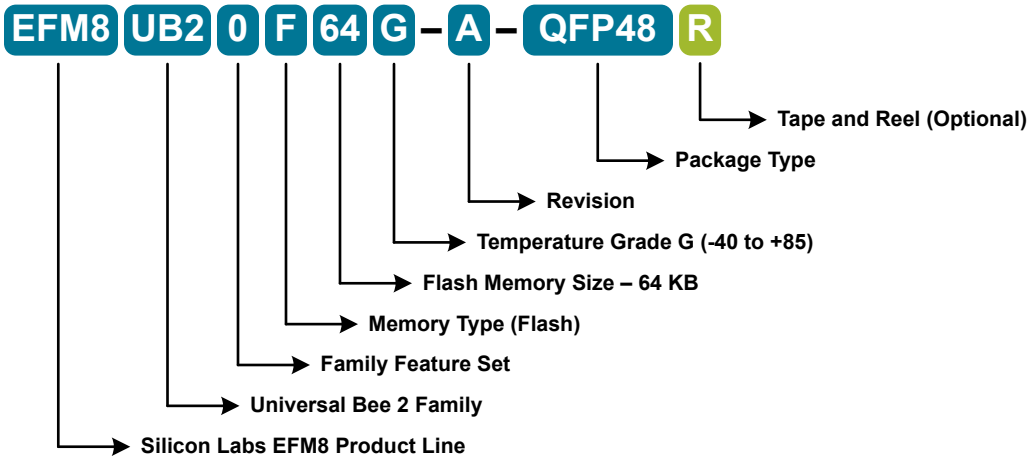


Figure 2.1. EFM8UB2 Part Numbering

All EFM8UB2 family members have the following features:

- CIP-51 Core running up to 48 MHz
- Two Internal Oscillators (48 MHz and 80 kHz)
- USB Full/Low speed Function Controller
- 5 V-In, 3.3 V-Out Regulator
- 2 SMBus/I2C Interfaces
- SPI
- 2 UARTs
- 5-Channel Programmable Counter Array (PWM, Clock Generation, Capture/Compare)
- 6 16-bit Timers
- 2 Analog Comparators
- 10-bit Differential Analog-to-Digital Converter with integrated multiplexer and temperature sensor
- Pre-loaded USB bootloader

In addition to these features, each part number in the EFM8UB2 family has a set of features that vary across the product line. The product selection guide shows the features available on each family member.

Table 2.1. Product Selection Guide

Ordering Part Number	Flash Memory (kB)	RAM (Bytes)	Digital Port I/Os (Total)	ADC0 Channels	Comparator 0 Inputs	Comparator 1 Inputs	Crystal Oscillator	External Memory Interface	Pb-free (RoHS Compliant)	Temperature Range	Package
EFM8UB20F64G-B-QFP48	64	4352	40	32	5	5	Yes	Yes	Yes	-40 to +85 °C	QFP48
EFM8UB20F64G-B-QFP32	64	4352	25	20	5	4	—	—	Yes	-40 to +85 °C	QFP32
EFM8UB20F64G-B-QFN32	64	4352	25	20	5	4	—	—	Yes	-40 to +85 °C	QFN32
EFM8UB20F32G-B-QFP48	32	2304	40	32	5	5	Yes	Yes	Yes	-40 to +85 °C	QFP48
EFM8UB20F32G-B-QFP32	32	2304	25	20	5	4	—	—	Yes	-40 to +85 °C	QFP32
EFM8UB20F32G-B-QFN32	32	2304	25	20	5	4	—	—	Yes	-40 to +85 °C	QFN32

3. System Overview

3.1 Introduction

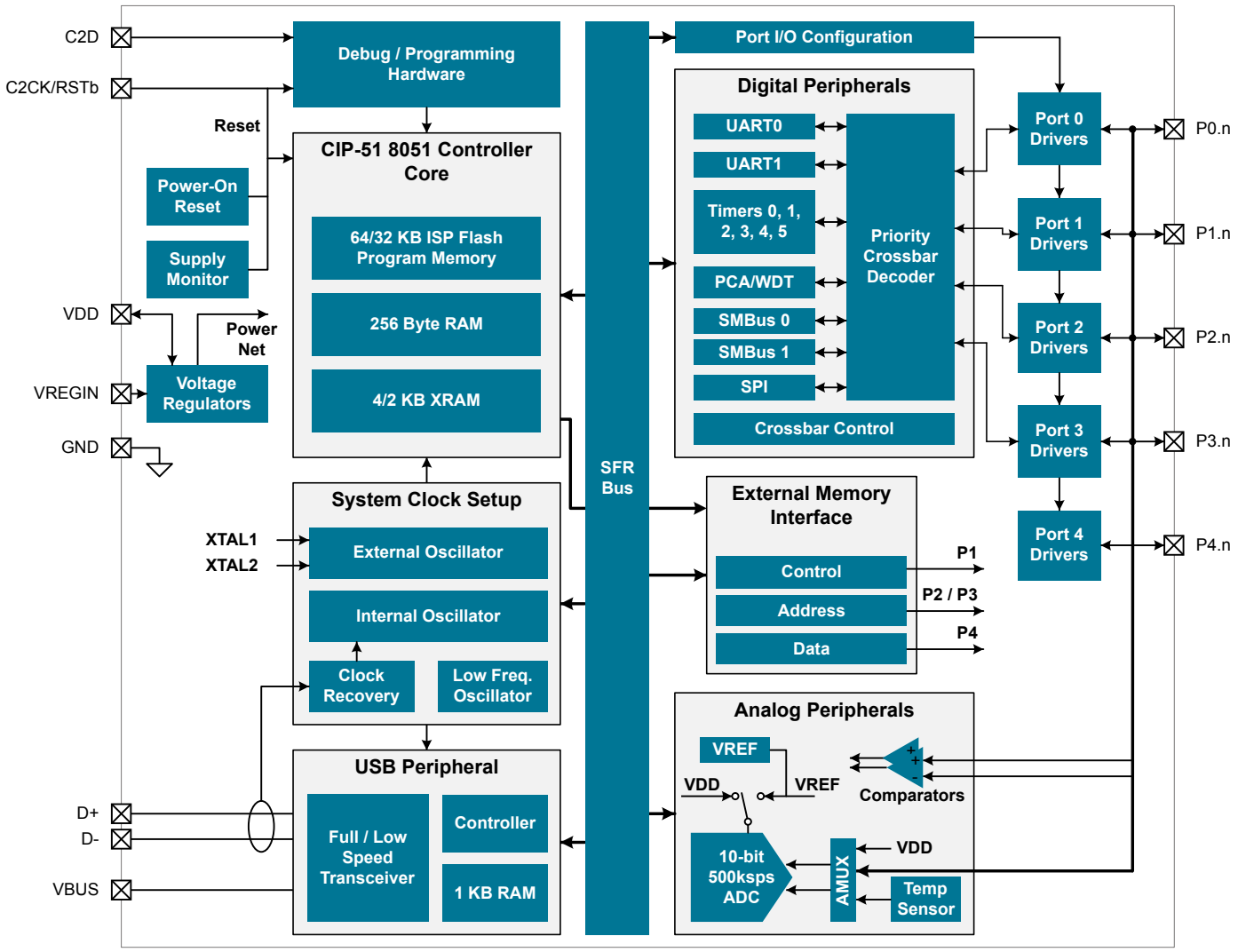


Figure 3.1. Detailed EFM8UB2 Block Diagram

This section describes the EFM8UB2 family at a high level. For more information on each module including register definitions, see the EFM8UB2 Reference Manual.

3.2 Power

All internal circuitry draws power from the VDD supply pin. External I/O pins are powered from the VIO supply voltage (or VDD on devices without a separate VIO connection), while most of the internal circuitry is supplied by an on-chip LDO regulator. Control over the device power can be achieved by enabling/disabling individual peripherals as needed. Each analog peripheral can be disabled when not in use and placed in low power mode. Digital peripherals, such as timers and serial buses, have their clocks gated off and draw little power when they are not in use.

Table 3.1. Power Modes

Power Mode	Details	Mode Entry	Wake-Up Sources
Normal	Core and all peripherals clocked and fully operational	—	—
Idle	• Core halted • All peripherals clocked and fully operational • Code resumes execution on wake event	Set IDLE bit in PCON0	Any interrupt
Suspend	• Core and peripheral clocks halted • Code resumes execution on wake event	1. Switch SYSCLK to HFOSC0 2. Set SUSPEND bit in HFO0CN	USB0 Bus Activity
Stop	• All internal power nets shut down • Pins retain state • Exit on any reset source	Set STOP bit in PCON0	Any reset source
Shutdown	• All internal power nets shut down • 5V regulator remains active (if enabled) • Pins retain state • Exit on pin or power-on reset	1. Set STOPCF bit in REG01CN 2. Set STOP bit in PCON0	• RSTb pin reset • Power-on reset

3.3 I/O

Digital and analog resources are externally available on the device's multi-purpose I/O pins. Port pins P0.0-P3.7 can be defined as general-purpose I/O (GPIO), assigned to one of the internal digital resources through the crossbar or dedicated channels, or assigned to an analog function. Port pins P4.0-P4.7 can be used as GPIO. Additionally, the C2 Interface Data signal (C2D) is shared with P3.0 on some packages.

- Up to 40 multi-functions I/O pins, supporting digital and analog functions.
- Flexible priority crossbar decoder for digital peripheral assignment.
- Two direct-pin interrupt sources with dedicated interrupt vectors (INT0 and INT1) available on P0 pins.

3.4 Clocking

The CPU core and peripheral subsystem may be clocked by both internal and external oscillator resources. By default, the system clock comes up running from the 48 MHz oscillator divided by 4, then divided by 8 (1.5 MHz).

- Provides clock to core and peripherals.
- 48 MHz internal oscillator (HFOSC0), accurate to ±1.5% over supply and temperature corners: accurate to +/- 0.25% when using USB clock recovery.
- 80 kHz low-frequency oscillator (LFOSC0).
- External RC, C, CMOS, and high-frequency crystal clock options (EXTCLK) for QFP48 packages.
- External CMOS clock option (EXTCLK) for QFP32 and QFN32 packages.
- Internal oscillator has clock divider with eight settings for flexible clock scaling: 1, 2, 4, or 8.

3.6 Communications and Other Digital Peripherals

Universal Serial Bus (USB0)

The USB0 module provides Full/Low Speed function for USB peripheral implementations. The USB function controller (USB0) consists of a Serial Interface Engine (SIE), USB transceiver (including matching resistors and configurable pull-up resistors), 1 KB FIFO block, and clock recovery mechanism for crystal-less operation. No external components are required. The USB0 module is Universal Serial Bus Specification 2.0 compliant.

The USB0 module includes the following features:

- Full and Low Speed functionality.
- Implements 4 bidirectional endpoints.
- USB 2.0 compliant USB peripheral support (no host capability).
- Direct module access to 1 KB of RAM for FIFO memory.
- Clock recovery to meet USB clocking requirements with no external components.

Universal Asynchronous Receiver/Transmitter (UART0)

UART0 is an asynchronous, full duplex serial port offering modes 1 and 3 of the standard 8051 UART. Enhanced baud rate support allows a wide range of clock sources to generate standard baud rates. Received data buffering allows UART0 to start reception of a second incoming data byte before software has finished reading the previous data byte.

The UART module provides the following features:

- Asynchronous transmissions and receptions.
- Baud rates up to SYSCLK/2 (transmit) or SYSCLK/8 (receive).
- 8- or 9-bit data.
- Automatic start and stop generation.
- Single-byte FIFO on transmit and receive.

Universal Asynchronous Receiver/Transmitter (UART1)

UART1 is an asynchronous, full duplex serial port offering a variety of data formatting options. A dedicated baud rate generator with a 16-bit timer and selectable prescaler is included, which can generate a wide range of baud rates. A received data FIFO allows UART1 to receive multiple bytes before data is lost and an overflow occurs.

UART1 provides the following features:

- Asynchronous transmissions and receptions.
- Dedicated baud rate generator supports baud rates up to SYSCLK/2 (transmit) or SYSCLK/8 (receive)
- 5, 6, 7, 8, or 9 bit data.
- Automatic start and stop generation.
- Automatic parity generation and checking.
- Three byte FIFO on receive.

Serial Peripheral Interface (SPI0)

The serial peripheral interface (SPI) module provides access to a flexible, full-duplex synchronous serial bus. The SPI can operate as a master or slave device in both 3-wire or 4-wire modes, and supports multiple masters and slaves on a single SPI bus. The slave-select (NSS) signal can be configured as an input to select the SPI in slave mode, or to disable master mode operation in a multi-master environment, avoiding contention on the SPI bus when more than one master attempts simultaneous data transfers. NSS can also be configured as a firmware-controlled chip-select output in master mode, or disabled to reduce the number of pins required. Additional general purpose port I/O pins can be used to select multiple slave devices in master mode.

The SPI module includes the following features:

- Supports 3- or 4-wire operation in master or slave modes.
- Supports external clock frequencies up to SYSCLK / 2 in master mode and SYSCLK / 10 in slave mode.
- Support for four clock phase and polarity options.
- 8-bit dedicated clock clock rate generator.
- Support for multiple masters on the same data lines.

Low Current Comparators (CMP0, CMP1)

Analog comparators are used to compare the voltage of two analog inputs, with a digital output indicating which input voltage is higher. External input connections to device I/O pins and internal connections are available through separate multiplexers on the positive and negative inputs. Hysteresis, response time, and current consumption may be programmed to suit the specific needs of the application.

The comparator module includes the following features:

- Up to 5 external positive inputs.
- Up to 5 external negative inputs.
- Synchronous and asynchronous outputs can be routed to pins via crossbar.
- Programmable hysteresis between 0 and +/-20 mV.
- Programmable response time.
- Interrupts generated on rising, falling, or both edges.

3.8 Reset Sources

Reset circuitry allows the controller to be easily placed in a predefined default condition. On entry to this reset state, the following occur:

- The core halts program execution.
- Module registers are initialized to their defined reset values unless the bits reset only with a power-on reset.
- External port pins are forced to a known state.
- Interrupts and timers are disabled.

All registers are reset to the predefined values noted in the register descriptions unless the bits only reset with a power-on reset. The contents of RAM are unaffected during a reset; any previously stored data is preserved as long as power is not lost. The Port I/O latches are reset to 1 in open-drain mode. Weak pullups are enabled during and after the reset. For Supply Monitor and power-on resets, the RSTb pin is driven low until the device exits the reset state. On exit from the reset state, the program counter (PC) is reset, and the system clock defaults to an internal oscillator. The Watchdog Timer is enabled, and program execution begins at location 0x0000.

Reset sources on the device include:

- Power-on reset
- External reset pin
- Comparator reset
- Software-triggered reset
- Supply monitor reset (monitors VDD supply)
- Watchdog timer reset
- Missing clock detector reset
- Flash error reset
- USB reset

3.9 Debugging

The EFM8UB2 devices include an on-chip Silicon Labs 2-Wire (C2) debug interface to allow flash programming and in-system debugging with the production part installed in the end application. The C2 interface uses a clock signal (C2CK) and a bi-directional C2 data signal (C2D) to transfer information between the device and a host system. See the C2 Interface Specification for details on the C2 protocol.

4.1.2 Power Consumption

Table 4.2. Power Consumption

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Digital Core Supply Current						
Normal Mode-Full speed with code executing from flash	I_{DD}	F_{SYSCLK} = 48 MHz[2]	—	12	14	mA
		F_{SYSCLK} = 24 MHz[2]	—	7	8	mA
		F_{SYSCLK} = 80 kHz[3]	—	280	—	µA
Idle Mode—Core halted with peripherals running	I_{DD}	F_{SYSCLK} = 48 MHz[2]	—	6.5	8	mA
		F_{SYSCLK} = 24 MHz[2]	—	3.5	5	mA
		F_{SYSCLK} = 80 kHz[3]	—	220	—	µA
Suspend Mode-Core halted and high frequency clocks stopped, Supply monitor off. Regulators in low-power mode.	I_{DD}	LFO Running	—	105	—	µA
		LFO Stopped	—	100	—	µA
Stop Mode—Core halted and all clocks stopped, Regulators in low-power mode, Supply monitor off.	I_{DD}		—	100	—	µA
Shutdown Mode—Core halted and all clocks stopped,Regulators Off, Supply monitor off.	I_{DD}		—	0.25	—	µA
Analog Peripheral Supply Currents						
High-Frequency Oscillator 0	I_{HFOSC0}	Operating at 48 MHz, T_A = 25 °C	—	900	—	µA
Low-Frequency Oscillator	I_{LFOSC}	Operating at 80 kHz, T_A = 25 °C	—	5	—	µA
ADC0 Supply Current	I_{ADC}	Operating at 500 ksps V_{DD} = 3.0 V	—	750	1000	µA
On-chip Precision Reference	I_{VREFP}		—	75	—	µA
Temperature Sensor	I_{TSENSE}		—	35	—	µA
Comparator 0 (CMP0, CMP1)	I_{CMP}	CPMD = 11	—	1	—	µA
		CPMD = 10	—	4	—	µA
		CPMD = 01	—	10	—	µA
		CPMD = 00	—	20	—	µA
Voltage Supply Monitor (VMON0)	I_{VMON}		—	15	50	µA
Regulator Bias Currents	I_{VREG}	Both Regulators in Normal Mode	—	200	—	µA
		Both Regulators in Low Power Mode	—	100	—	µA
		5 V Regulator Off, Internal LDO in Low Power Mode	—	150	—	µA
USB (USB0) Full-Speed	I_{USB}	Active	—	8	—	mA

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit

Note:

1. Currents are additive. For example, where I_{DD} is specified and the mode is not mutually exclusive, enabling the functions increases supply current by the specified amount.
2. Includes supply current from regulators, supply monitor, and High Frequency Oscillator.
3. Includes supply current from regulators, supply monitor, and Low Frequency Oscillator.

4.1.3 Reset and Supply Monitor

Table 4.3. Reset and Supply Monitor

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
VDD Supply Monitor Threshold	V_{VDDM}		2.60	2.65	2.70	V
Power-On Reset (POR) Threshold	V_{POR}	Rising Voltage on VDD	—	1.4	—	V
		Falling Voltage on VDD	0.75	—	1.36	V
VDD Ramp Time	t_{RMP}	Time to V_{DD} > 2.7 V	—	—	1	ms
Reset Delay from POR	t_{POR}	Relative to V_{DD} > V_{POR}	3	10	31	ms
Reset Delay from non-POR source	t_{RST}	Time between release of reset source and code execution	—	—	250	µs
RST Low Time to Generate Reset	t_{RSTL}		15	—	—	µs
Missing Clock Detector Response Time (final rising edge to reset)	t_{MCD}	F_{SYSCLK} >1 MHz	80	580	800	µs
VDD Supply Monitor Turn-On Time	t_{MON}		—	—	100	µs

4.1.4 Flash Memory

Table 4.4. Flash Memory

Parameter	Symbol	Test Condition	Min	Typ	Max	Units
Write Time[1]	t_{WRITE}	One Byte	10	15	20	µs
Erase Time[1]	t_{ERASE}	One Page	10	15	22.5	ms
V_{DD} Voltage During Programming[2]	V_{PROG}		2.7	—	3.6	V
Endurance (Write/Erase Cycles)	N_{WE}		10k	100k	—	Cycles
CRC Calculation Time	t_{CRC}	One 256-Byte Block SYSCLK = 48 MHz	—	5.5	—	µs

Note:

1. Does not include sequencing time before and after the write/erase operation, which may be multiple SYSCLK cycles.
2. Flash can be safely programmed at any voltage above the supply monitor threshold (V_{VDDM}).
3. Data Retention Information is published in the Quarterly Quality and Reliability Report.

4.1.8 ADC

Table 4.8. ADC

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Resolution	N_{bits}			10		Bits
Throughput Rate	f_S		—	—	500	ksps
Tracking Time	t_{TRK}		300	—	—	ns
SAR Clock Frequency	f_{SAR}		—	—	8.33	MHz
Conversion Time	t_{CNV}	10-Bit Conversion,	13	—	—	Clocks
Sample/Hold Capacitor	C_{SAR}		—	30	—	pF
Input Mux Impedance	R_{MUX}		—	5	—	kΩ
Voltage Reference Range	V_{REF}		1	—	V_{DD}	V
Input Voltage Range[1]	V_{IN}	Single-Ended (AIN+ - GND)	0	—	V_{REF}	V
		Differential (AIN+ - AIN-)	$-V_{REF}$	—	V_{REF}	V
Power Supply Rejection Ratio	$PSRR_{ADC}$		—	70	—	dB
DC Performance, VREF = 2.4 V						
Integral Nonlinearity	INL		—	±0.5	±1	LSB
Differential Nonlinearity (Guaranteed Monotonic)	DNL		—	±0.5	±1	LSB
Offset Error	E_{OFF}		-2	0	2	LSB
Offset Temperature Coefficient	TC_{OFF}		—	0.005	—	LSB/°C
Slope Error	E_M		—	-0.2	±0.5	%
Dynamic Performance 10 kHz Sine Wave Input 1dB below full scale, VREF = 2.4 V						
Signal-to-Noise	SNR		55	58	—	dB
Signal-to-Noise Plus Distortion	SNDR		55	58	—	dB
Total Harmonic Distortion (Up to 5th Harmonic)	THD		—	-73	—	dB
Spurious-Free Dynamic Range	SFDR		—	78	—	dB

Note:
1. Absolute input pin voltage is limited by the VDD and GND supply pins.

4.1.11 5 V Voltage Regulator

Table 4.11. 5V Voltage Regulator

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Input Voltage Range[1]	V_{REGIN}		2.7	—	5.25	V
Output Voltage on VDD[2]	V_{REGOUT}	Output Current = 1 to 100 mA	3.0	3.3	3.6	V
Output Current[2]	I_{REGOUT}		—	—	100	mA

Note:
1. Input range specified for regulation. When an external regulator is used, VREGIN should be tied to VDD.
2. Output current is total regulator output, including any current required by the device.

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Negative Hysteresis Mode 3 (CPMD = 11)	HYS_{CP-}	CPHYN = 00	—	-1.5	—	mV
		CPHYN = 01	—	-4	—	mV
		CPHYN = 10	—	-8	—	mV
		CPHYN = 11	—	-16	—	mV
Input Range (CP+ or CP-)	V_{IN}		-0.25	—	V_{DD}+0.25	V
Input Pin Capacitance	C_{CP}		—	7.5	—	pF
Common-Mode Rejection Ratio	$CMRR_{CP}$		—	60	—	dB
Power Supply Rejection Ratio	$PSRR_{CP}$		—	60	—	dB
Input Offset Voltage	V_{OFF}	T_A = 25 °C	-10	0	10	mV

4.1.13 Port I/O

Table 4.13. Port I/O

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Output High Voltage	V_{OH}	I_{OH} = -3 mA	V_{DD} - 0.7	—	—	V
		I_{OH} = -10 µA	V_{DD} - 0.1	—	—	V
Output Low Voltage	V_{OL}	I_{OL} = 8.5 mA	—	—	0.6	V
		I_{OL} = 10 µA	—	—	0.1	V
Input High Voltage	V_{IH}		2.0	—	—	V
Input Low Voltage	V_{IL}		—	—	0.8	V
Pin Capacitance	C_{IO}		—	7	—	pF
Weak Pull-Up Current (V_{IN} = 0 V)	I_{PU}	V_{DD} = 3.6	-50	-15	—	µA
Input Leakage (Pullups off or Analog)	I_{LK}	GND < V_{IN} < V_{DD}	-1	—	1	µA
Input Leakage Current with V_{IN} above V_{DD}	I_{LK}	V_{DD} < V_{IN} < V_{DD}+2.0 V	0	5	150	µA

4.1.15 SMBus

Table 4.15. SMBus Peripheral Timing Performance (Master Mode)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Standard Mode (100 kHz Class)						
I2C Operating Frequency	f_{I2C}		0	—	70[2]	kHz
SMBus Operating Frequency	f_{SMB}		40[1]	—	70[2]	kHz
Bus Free Time Between STOP and START Conditions	t_{BUF}		9.4	—	—	µs
Hold Time After (Repeated) START Condition	$t_{HD:STA}$		4.7	—	—	µs
Repeated START Condition Setup Time	$t_{SU:STA}$		9.4	—	—	µs
STOP Condition Setup Time	$t_{SU:STO}$		9.4	—	—	µs
Data Hold Time	$t_{HD:DAT}$		0	—	—	µs
Data Setup Time	$t_{SU:DAT}$		4.7	—	—	µs
Detect Clock Low Timeout	$t_{TIMEOUT}$		25	—	—	ms
Clock Low Period	t_{LOW}		4.7	—	—	µs
Clock High Period	t_{HIGH}		9.4	—	50[3]	µs
Fast Mode (400 kHz Class)						
I2C Operating Frequency	f_{I2C}		0	—	256[2]	kHz
SMBus Operating Frequency	f_{SMB}		40[1]	—	256[2]	kHz
Bus Free Time Between STOP and START Conditions	t_{BUF}		2.6	—	—	µs
Hold Time After (Repeated) START Condition	$t_{HD:STA}$		1.3	—	—	µs
Repeated START Condition Setup Time	$t_{SU:STA}$		2.6	—	—	µs
STOP Condition Setup Time	$t_{SU:STO}$		2.6	—	—	µs
Data Hold Time	$t_{HD:DAT}$		0	—	—	µs
Data Setup Time	$t_{SU:DAT}$		1.3	—	—	µs
Detect Clock Low Timeout	$t_{TIMEOUT}$		25	—	—	ms
Clock Low Period	t_{LOW}		1.3	—	—	µs
Clock High Period	t_{HIGH}		2.6	—	50[3]	µs

Note:

1. The minimum SMBus frequency is limited by the maximum Clock High Period requirement of the SMBus specification.
2. The maximum I2C and SMBus frequencies are limited by the minimum Clock Low Period requirements of their respective specifications.
3. SMBus has a maximum requirement of 50 µs for Clock High Period. Operating frequencies lower than 40 kHz will be longer than 50 µs. I2C can support periods longer than 50 µs.

Table 4.16. SMBus Peripheral Timing Formulas (Master Mode)

Parameter	Symbol	Clocks
SMBus Operating Frequency	f_{SMB}	f_{CSO} / 3
Bus Free Time Between STOP and START Conditions	t_{BUF}	2 / f_{CSO}
Hold Time After (Repeated) START Condition	$t_{HD:STA}$	1 / f_{CSO}
Repeated START Condition Setup Time	$t_{SU:STA}$	2 / f_{CSO}
STOP Condition Setup Time	$t_{SU:STO}$	2 / f_{CSO}
Clock Low Period	t_{LOW}	1 / f_{CSO}
Clock High Period	t_{HIGH}	2 / f_{CSO}

Note:
1. f_{CSO} is the SMBus peripheral clock source overflow frequency.

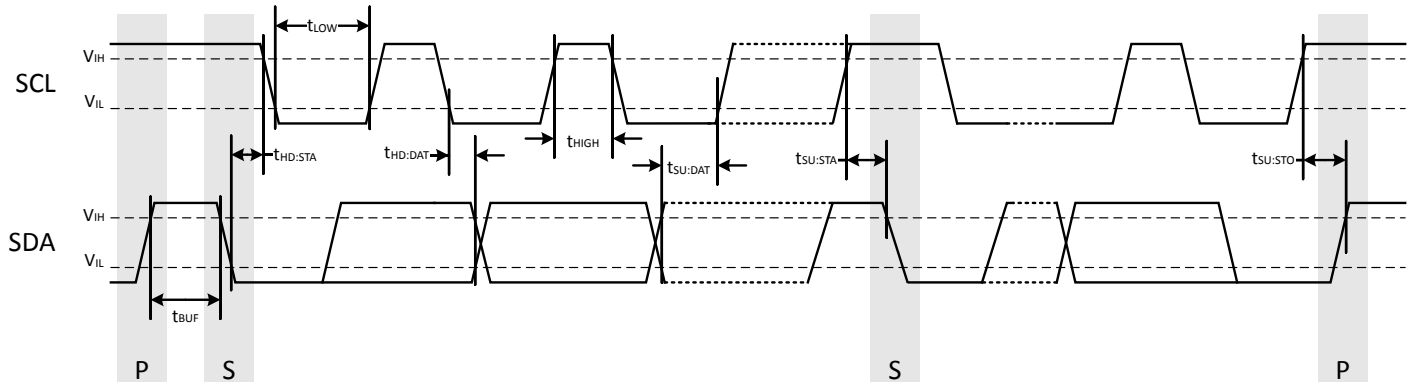


Figure 4.1. SMBus Peripheral Timing Diagram (Master Mode)

4.2 Thermal Conditions

Table 4.17. Thermal Conditions

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Thermal Resistance	θ_{JA}	QFP48 Packages	—	60	—	°C/W
		QFP32 Packages	—	80	—	°C/W
		QFN32 Packages	—	28	—	°C/W

Note:
1. Thermal resistance assumes a multi-layer PCB with any exposed pad soldered to a PCB pad.

Pin Number	Pin Name	Description	Crossbar Capability	Additional Digital Functions	Analog Functions
32	P0.2	Multifunction I/O	Yes	INT0.2 INT1.2	
Note: XTAL1 and XTAL2 are not available on this package. EXTCLK is still available on P0.3.					

7. QFP48 Package Specifications

7.1 QFP48 Package Dimensions

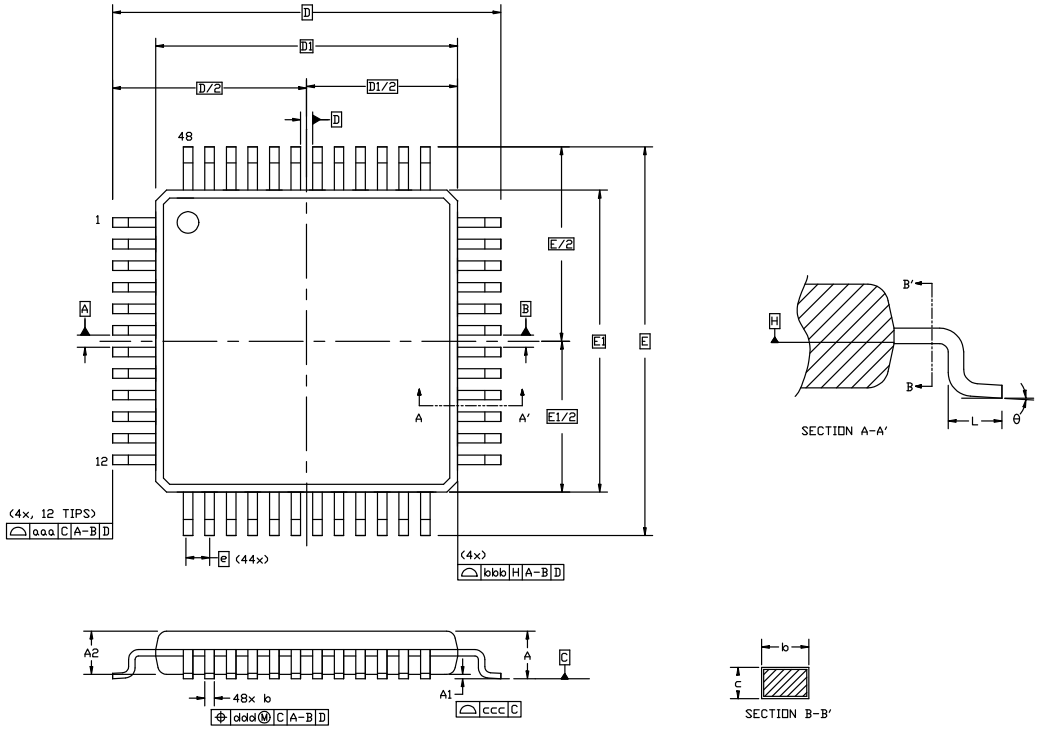


Figure 7.1. QFP48 Package Drawing

Table 7.1. QFP48 Package Dimensions

Dimension	Min	Typ	Max
A	—	—	1.20
A1	0.05	—	0.15
A2	0.95	1.00	1.05
b	0.17	0.22	0.27
D		9.00 BSC	
D1		7.00 BSC	
e		0.50 BSC	
E		9.00 BSC	
E1		7.00 BSC	
L	0.45	0.60	0.75
aaa		0.20	
bbb		0.20	

Dimension	Min	Typ	Max
ccc		0.08	
ddd		0.08	
theta	0°	3.5°	7°

Note:

1. All dimensions shown are in millimeters (mm) unless otherwise noted.
2. Dimensioning and Tolerancing per ANSI Y14.5M-1994.
3. This drawing conforms to JEDEC outline MS-026, variation ABC.
4. Recommended card reflow profile is per the JEDEC/IPC J-STD-020C specification for Small Body Components.

8.3 QFP32 Package Marking

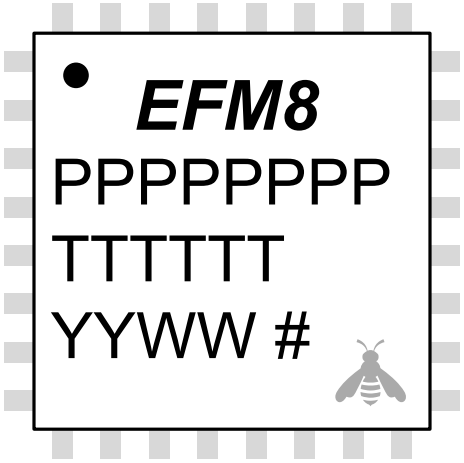


Figure 8.3. QFP32 Package Marking

The package marking consists of:

- PPPPPPPP – The part number designation.
- TTTTTT – A trace or manufacturing code.
- YY – The last 2 digits of the assembly year.
- WW – The 2-digit workweek when the device was assembled.
- # – The device revision (A, B, etc.).

9. QFN32 Package Specifications

9.1 QFN32 Package Dimensions

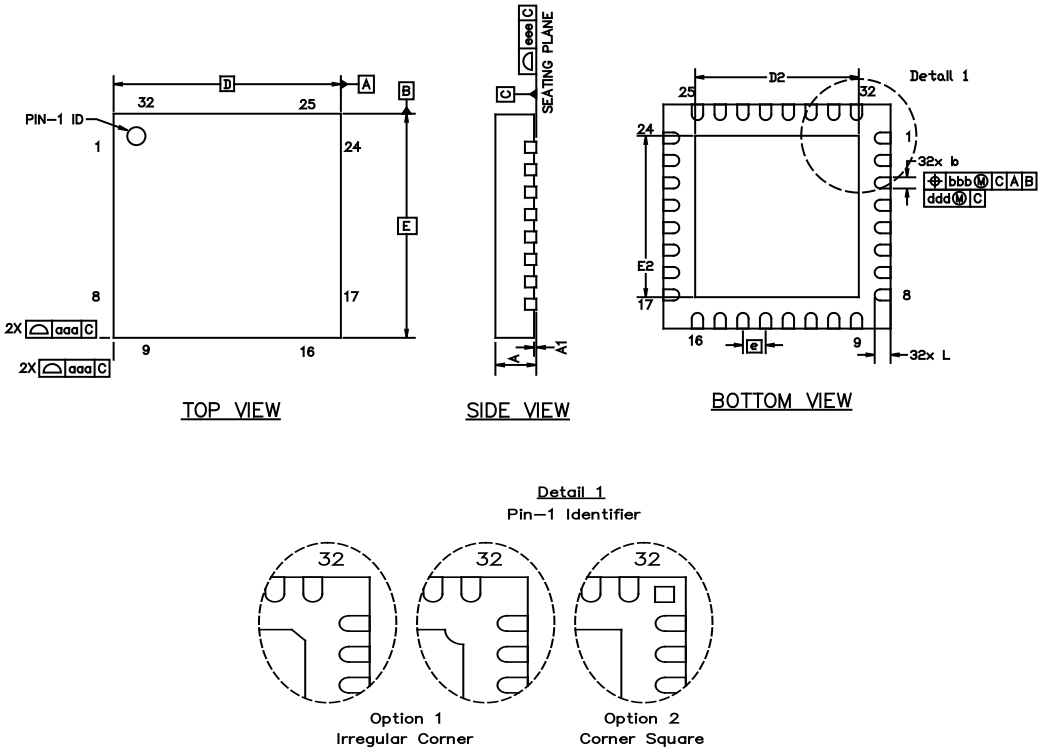
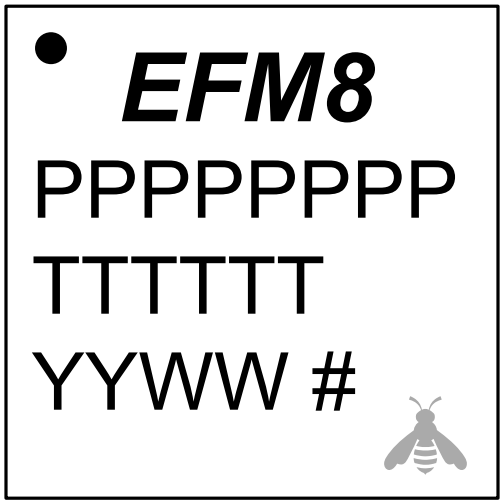


Figure 9.1. QFN32 Package Drawing

Table 9.1. QFN32 Package Dimensions

Dimension	Min	Typ	Max
A	0.80	0.85	0.90
A1	0.00	0.02	0.05
b	0.18	0.25	0.30
D		5.00 BSC	
D2	3.20	3.30	3.40
e		0.50 BSC	
E		5.00 BSC	
E2	3.20	3.30	3.40
L	0.35	0.40	0.45
aaa	—	—	0.10
bbb	—	—	0.10

9.3 QFN32 Package Marking



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10. Revision History

10.1 Revision 1.3

Updated ordering part numbers to revision B.

Added Power-On Reset Threshold and Reset Delay from POR specifications to 4.1.3 Reset and Supply Monitor.

Added CRC Calculation Time specification to 4.1.4 Flash Memory.

Added VBUS Detection Input High Voltage and VBUS Detection Input Low Voltage specifications to Table 4.14 USB Transceiver on page 20.

Added specifications for 4.1.15 SMBus.

Added 5.4 Debug.

Added information about bootloader implementation and bootloader pinout to 3.10 Bootloader.

Added notes to Table 6.3 Pin Definitions for EFM8UB2x-QFN32 on page 37 and Table 6.2 Pin Definitions for EFM8UB2x-QFP32 on page 33 to clarify that XTAL1 and XTAL2 are not available on the 32-pin packages.

Updated Figure 5.1 Connection Diagram with Voltage Regulator Used and USB Connected (Bus-Powered) on page 24 and Figure 5.2 Connection Diagram with Voltage Regulator Used and USB Connected (Self-Powered) on page 25 to recommend 4.7 µF capacitors instead of 1.0 µF capacitors.

Added text and Figure 5.3 Connection Diagram with Voltage Regulator Not Used on page 25 to demonstrate the proper connections when the regulator is not used.

Added reference to the Reference Manual in 3.1 Introduction.

10.2 Revision 1.2

Updated the VDD Ramp Time specification in Table 4.3 Reset and Supply Monitor on page 13 to a maximum of 1 ms.

10.3 Revision 1.1

Initial release.